

2A Avg.

35 Volts

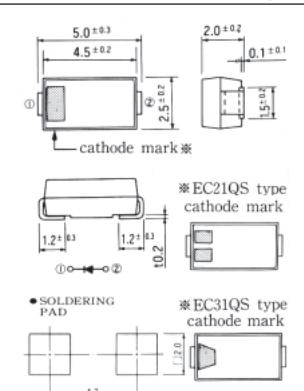
SBD

EC20QSA035

## ■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	35	V
平均整流電流 Average Rectified Forward Current	I <sub>O</sub>	T <sub>j</sub> =25°C, V <sub>RM</sub> =15V 50Hz Half Sine Wave Resistive Load	A
		T <sub>j</sub> =117°C, V <sub>RM</sub> =15V (T <sub>l</sub> :lead Temperature)	2.0
実効順電流 R.M.S. Forward Current	I <sub>F(RMS)</sub>	3.14	A
サージ順電流 Surge Forward Current	I <sub>FSM</sub>	40 50Hz正弦半波、1サイクル、非くり返し 50Hz Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T <sub>jw</sub>	-40~+150	°C
保存温度範囲 Storage Temperature Range	T <sub>stg</sub>	-40~+150	°C

## ■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.06 g

## ■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーケ逆電流 Peak Reverse Current	I <sub>RM</sub>	T <sub>j</sub> =25°C, V <sub>RM</sub> =35V	—	—	1	mA
ピーケ順電圧 Peak Forward Voltage	V <sub>FM</sub>	T <sub>j</sub> =25°C, I <sub>FM</sub> =2A	—	—	0.49	V
熱抵抗 Thermal Resistance	R <sub>th(j-a)</sub>	接合部・周囲間 Junction to Ambient	* (アルミナ基板実装) Alumina Substrate mounted		—	108 °C/W
	R <sub>th(j-l)</sub>	接合部・リード間 Junction to Lead	—		—	23 °C/W

\* アルミナ基板実装/Alumina Substrate mounted (Soldering Lands= 2 × 2 mm, Both Sides)

## ■定格・特性曲線

